

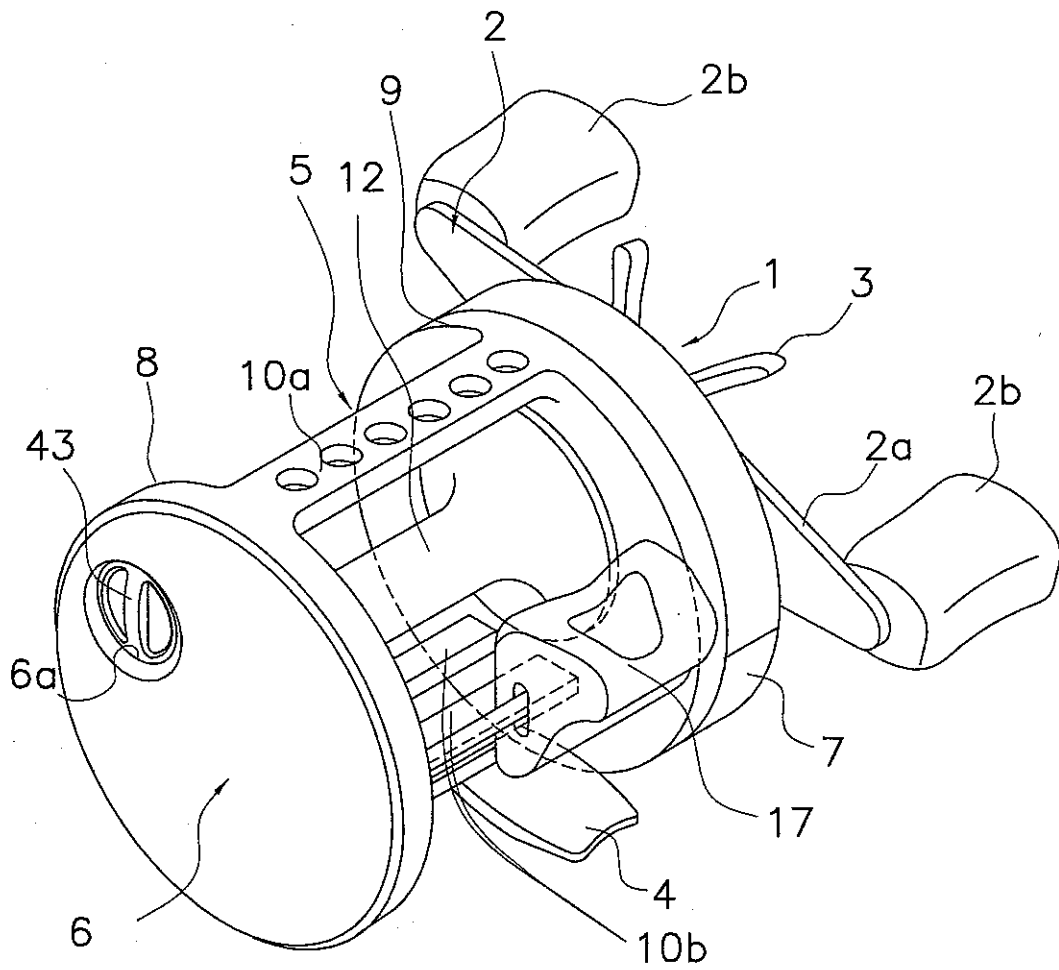
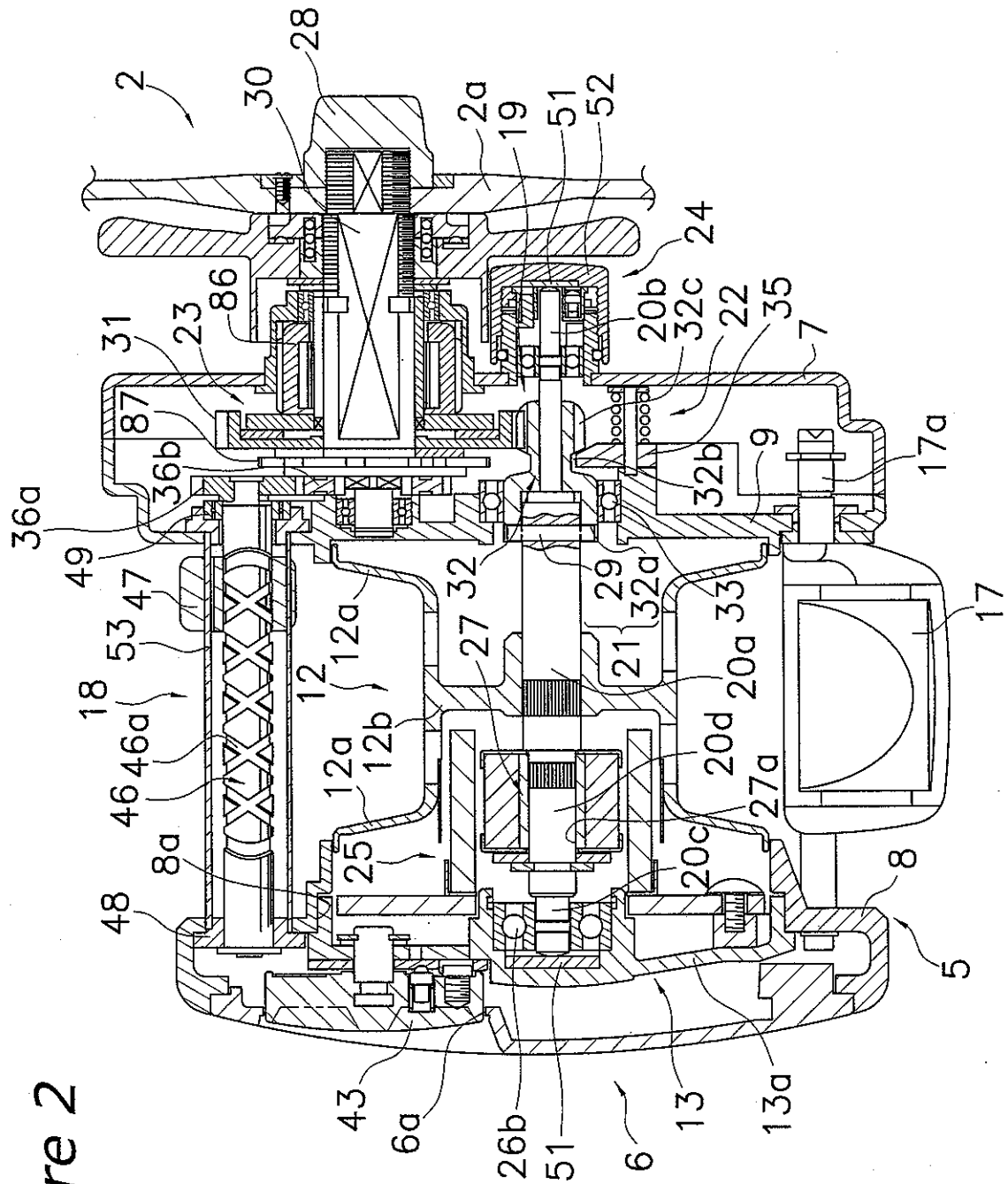


Figure 1

Figure 2



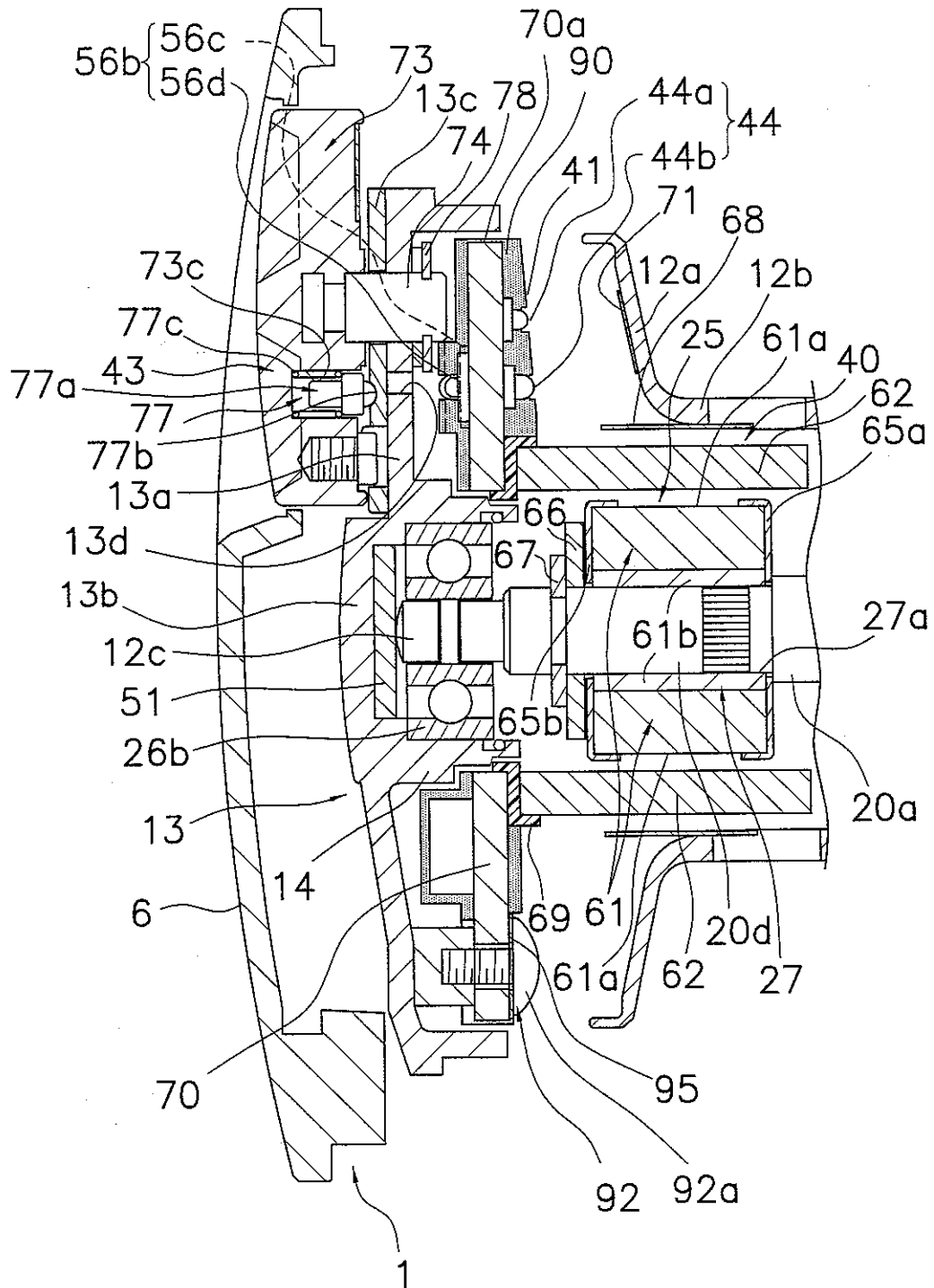
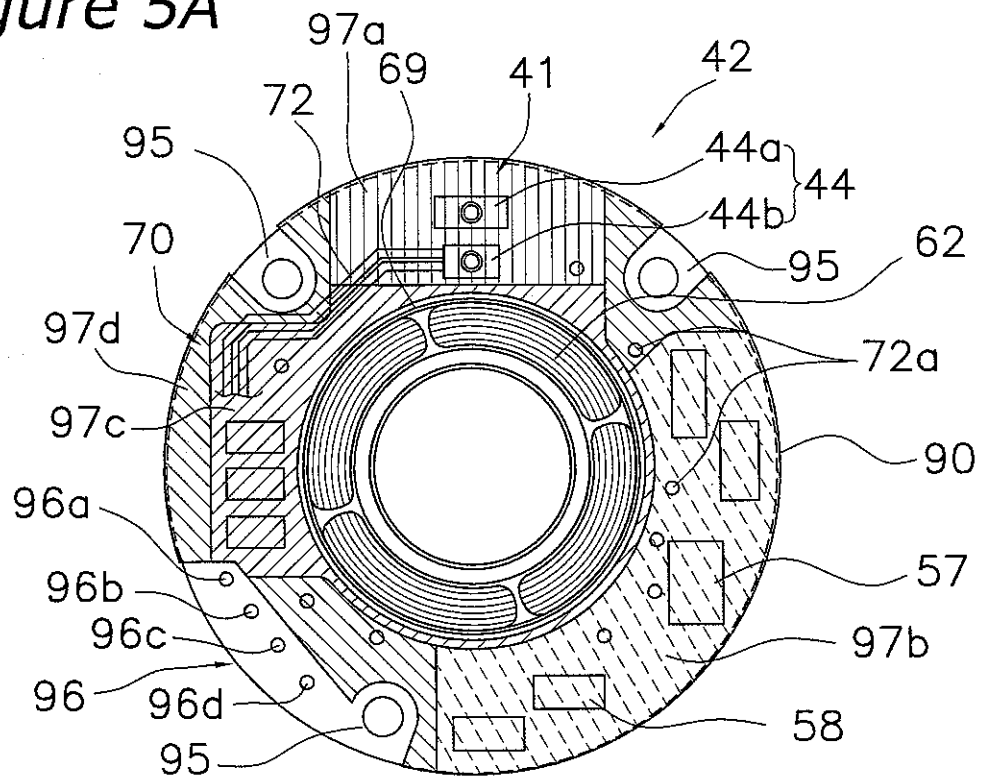
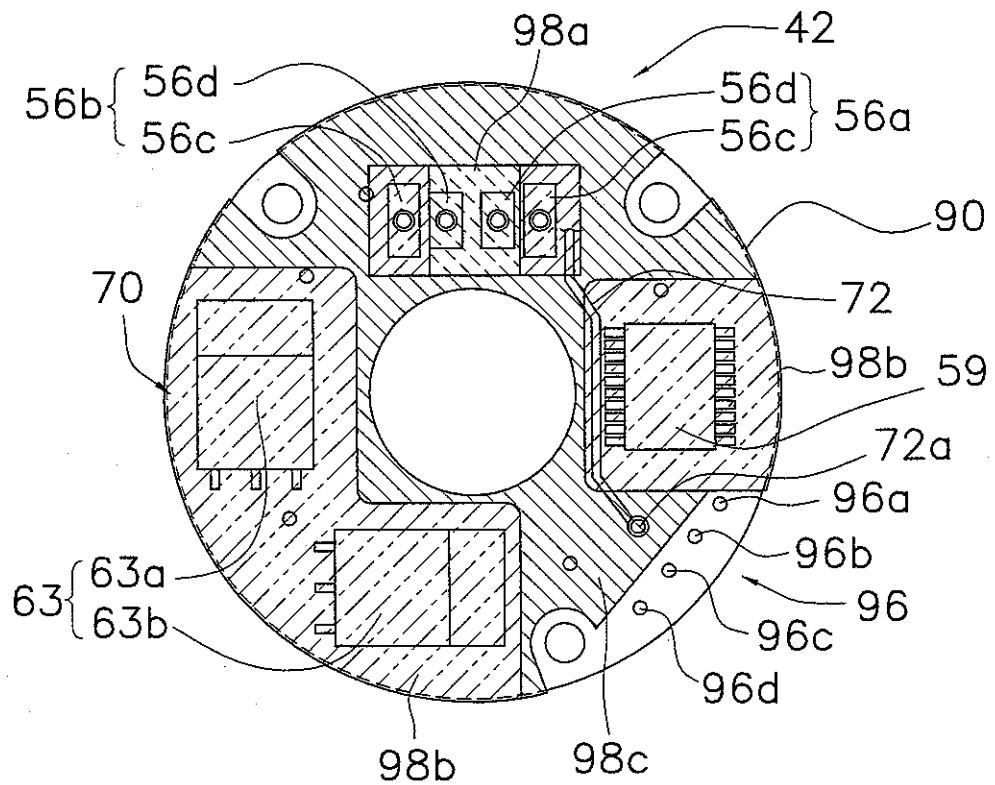


Figure 4

Figure 5A**Figure 5B**

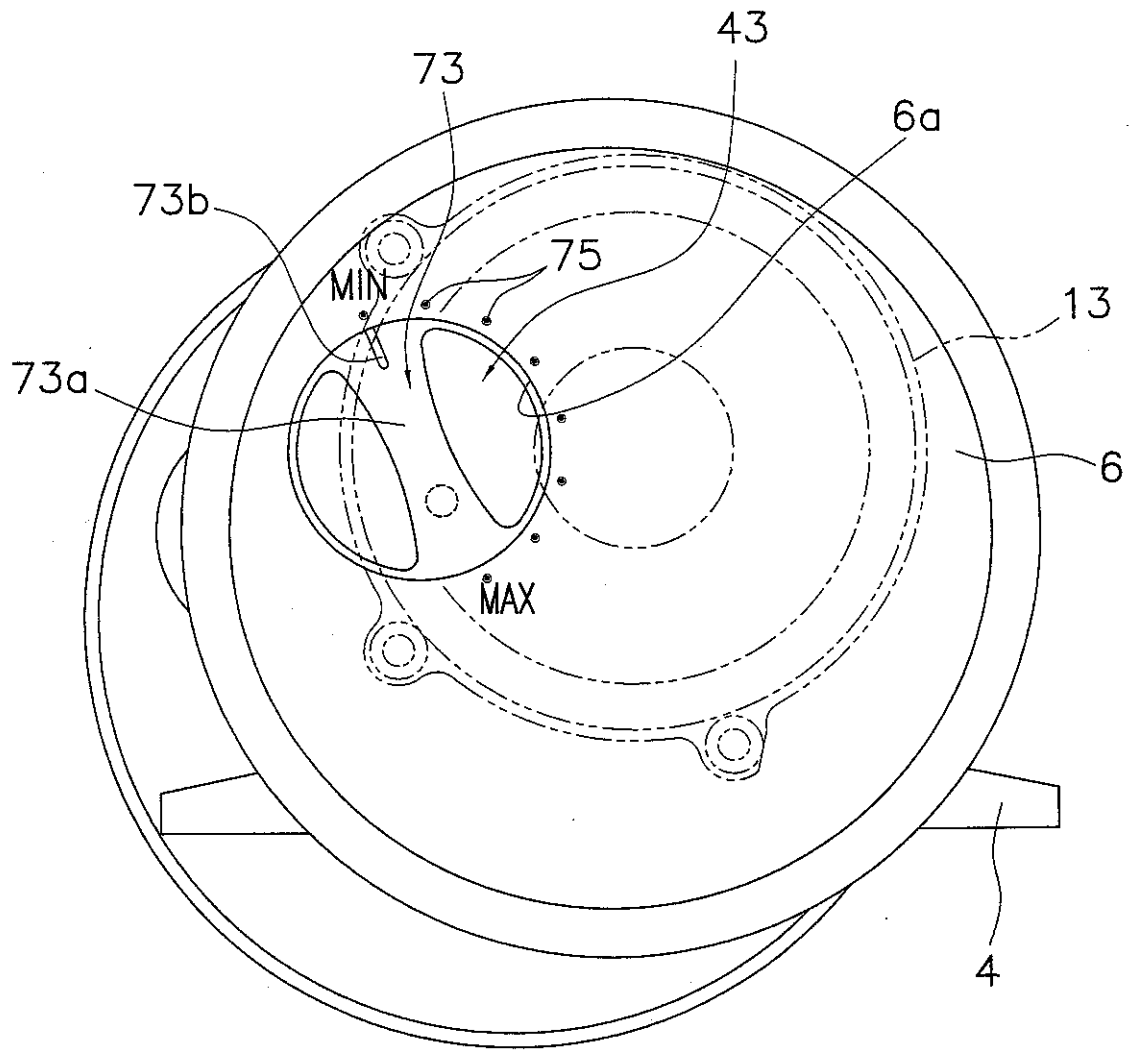


Figure 6A

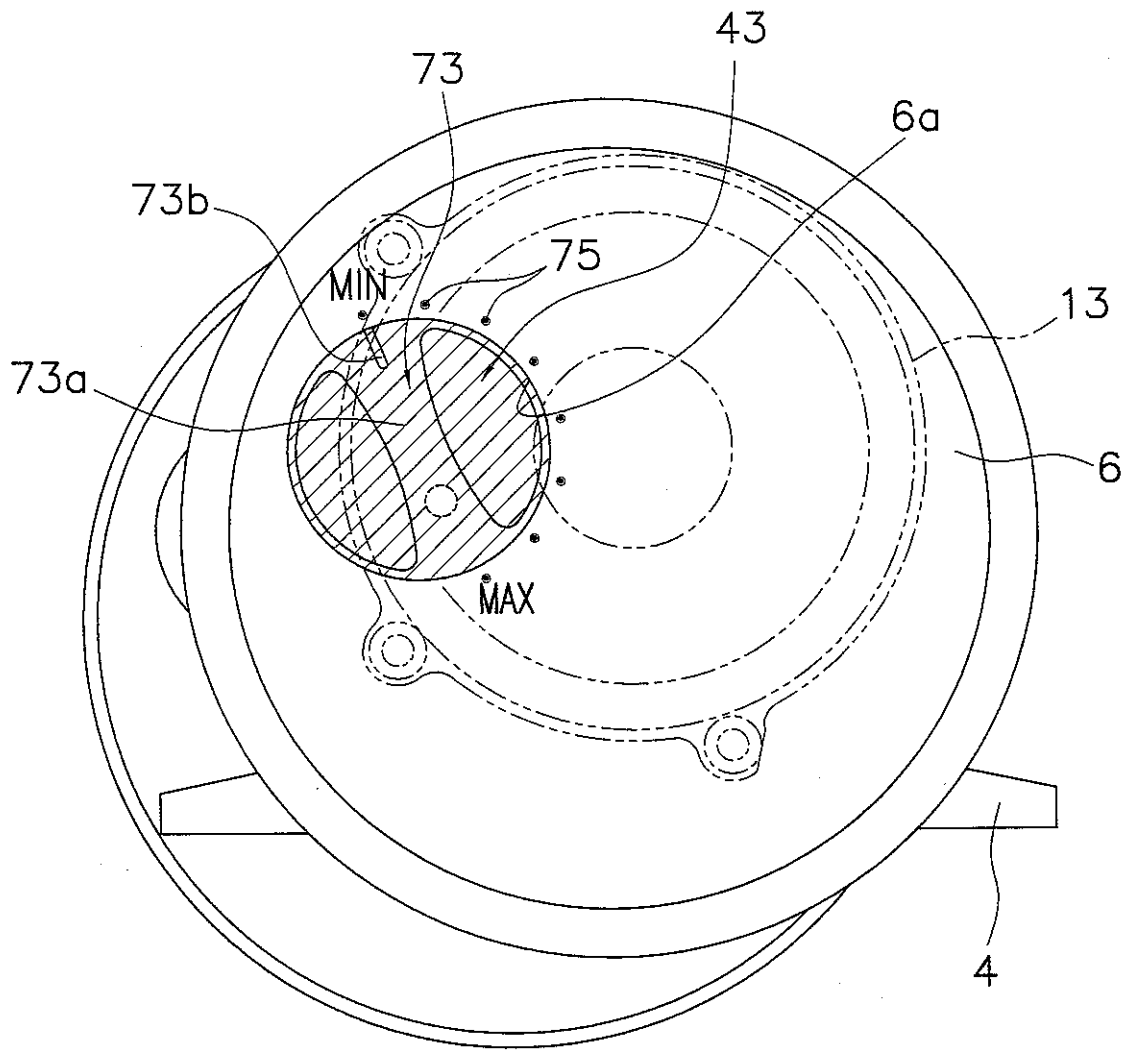


Figure 6B

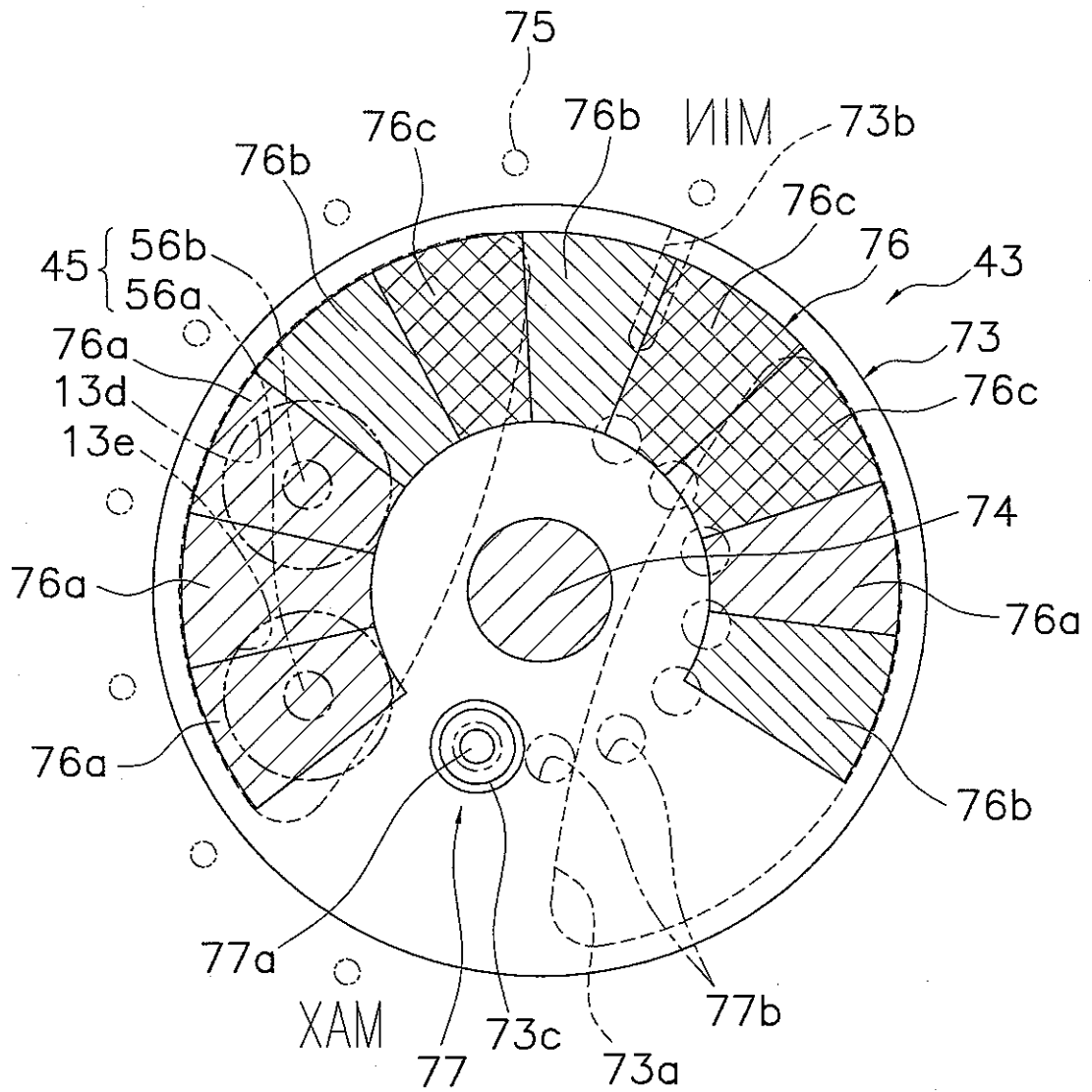


Figure 7

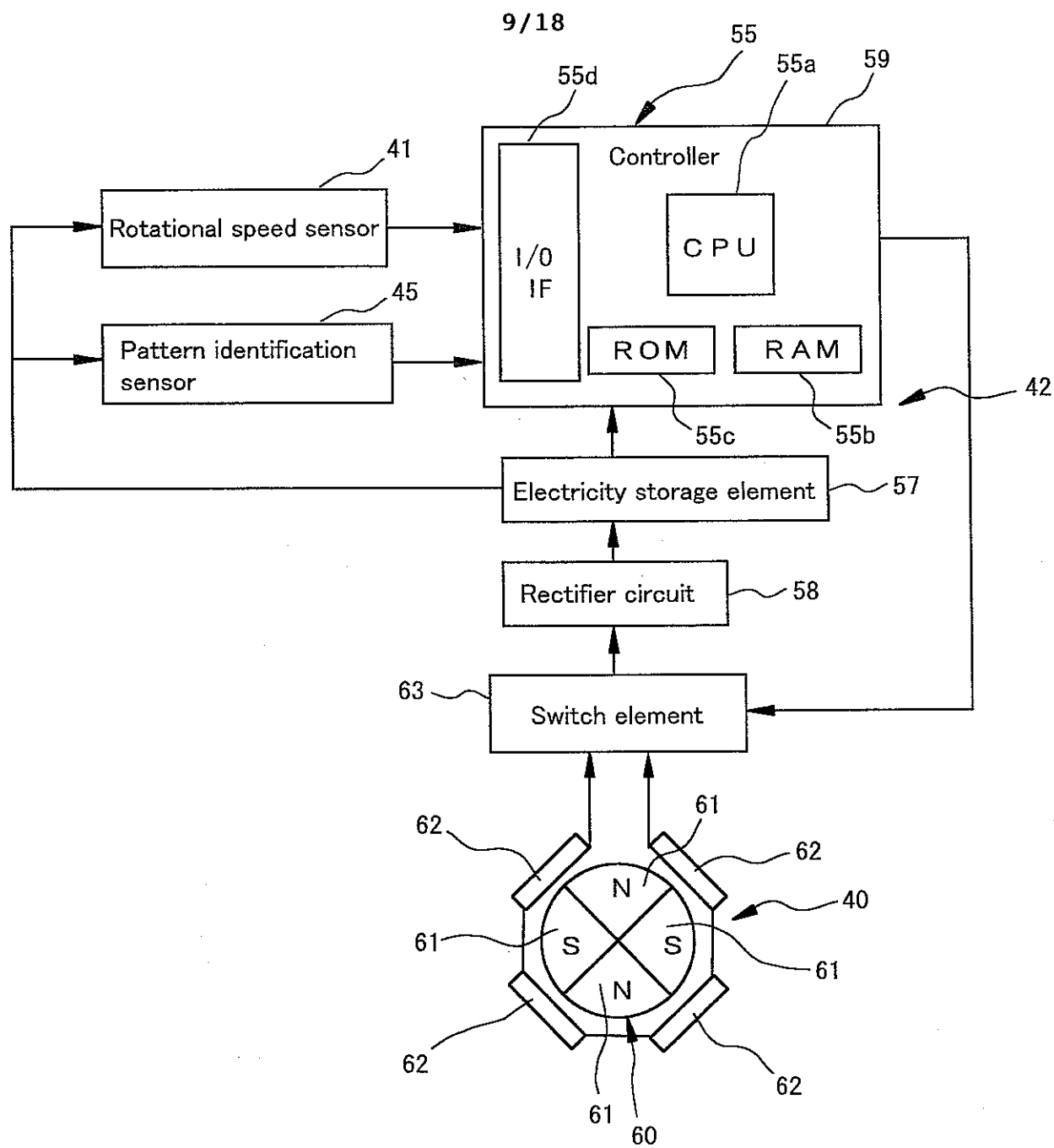


Figure 8

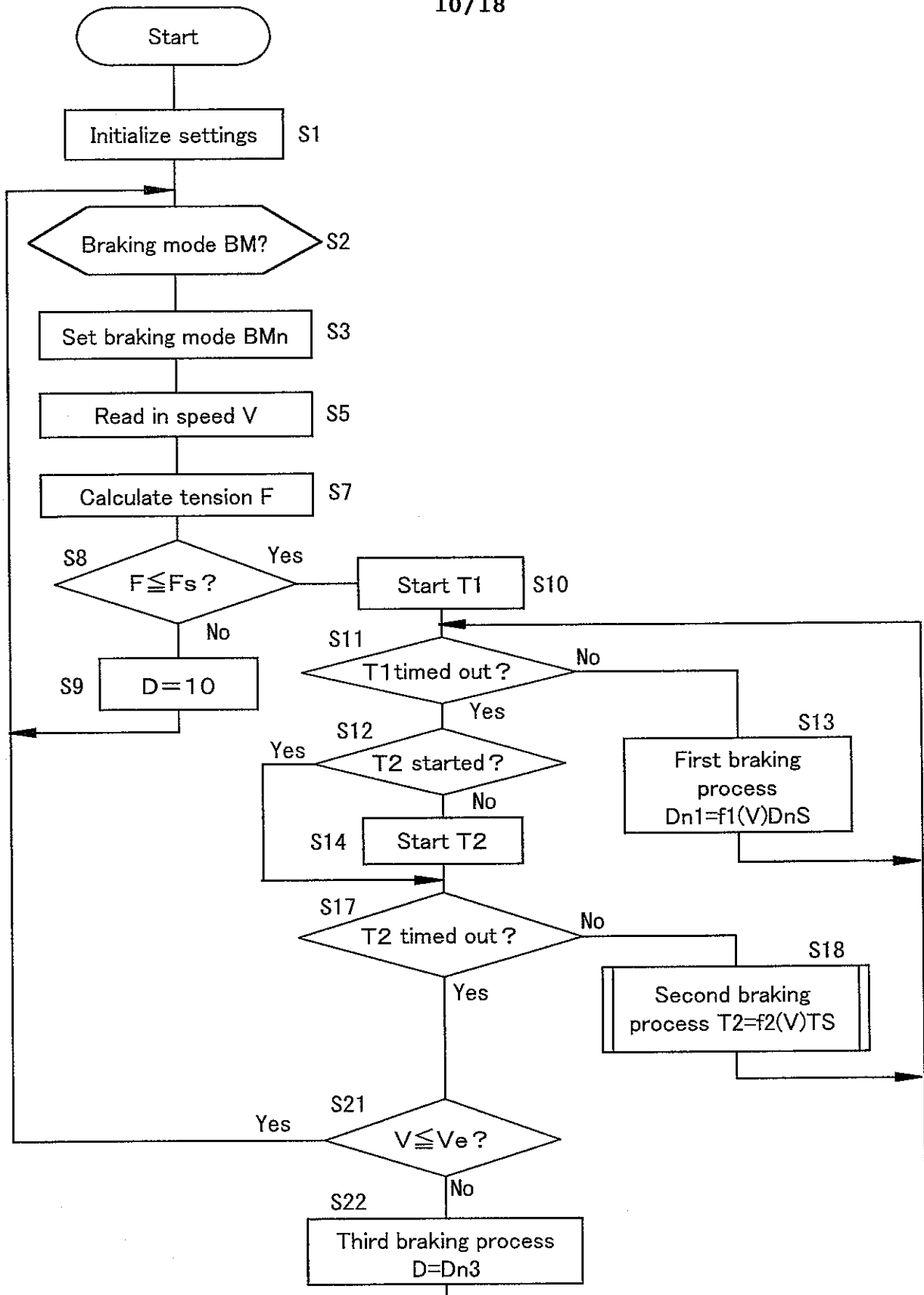


Figure 9

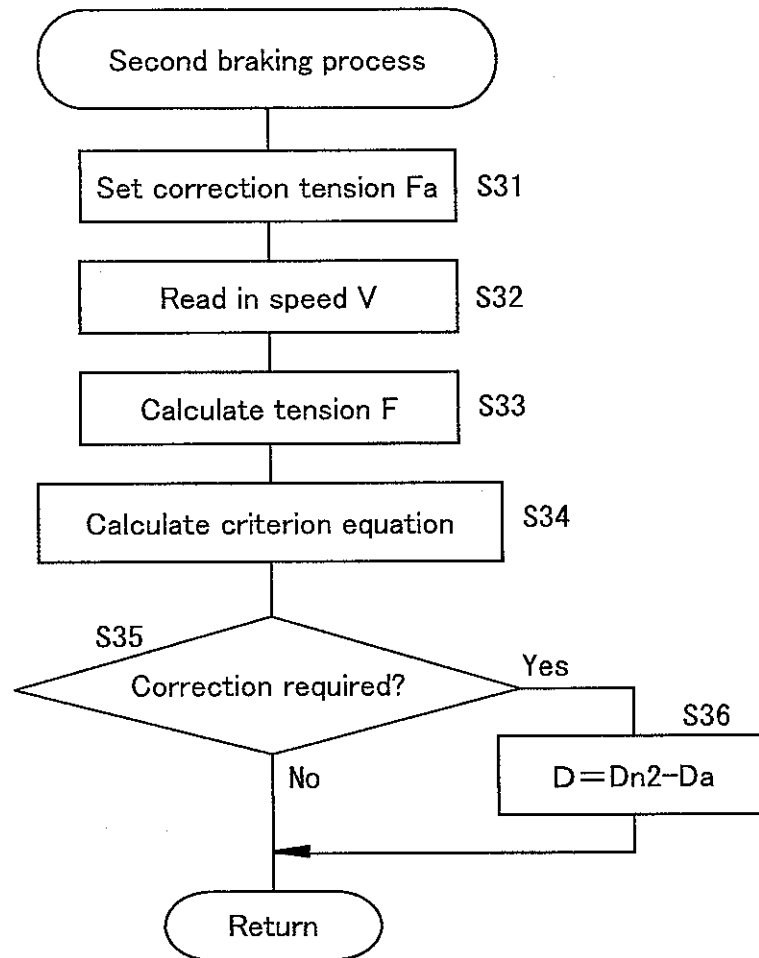


Figure 10

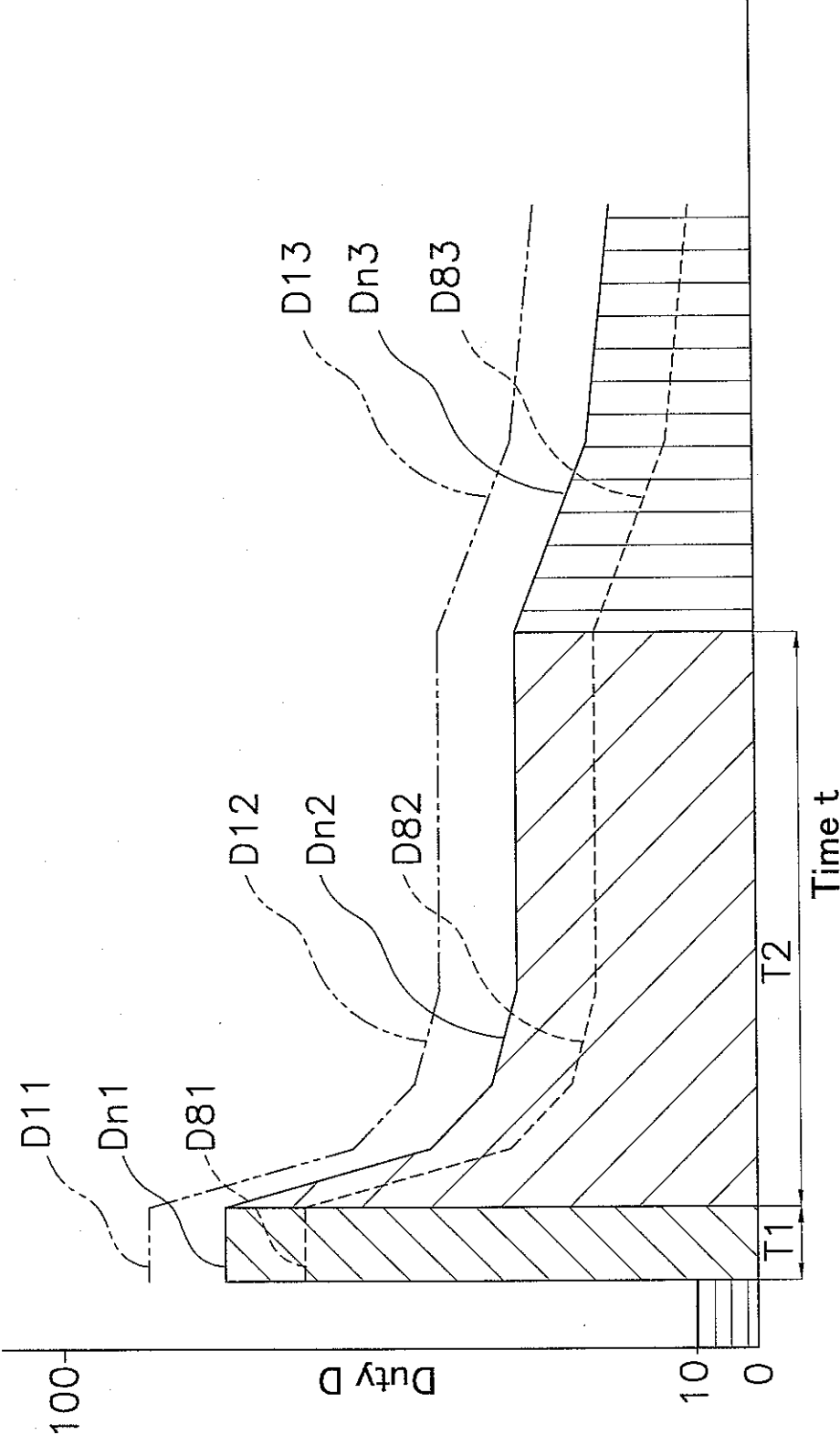


Figure 11A

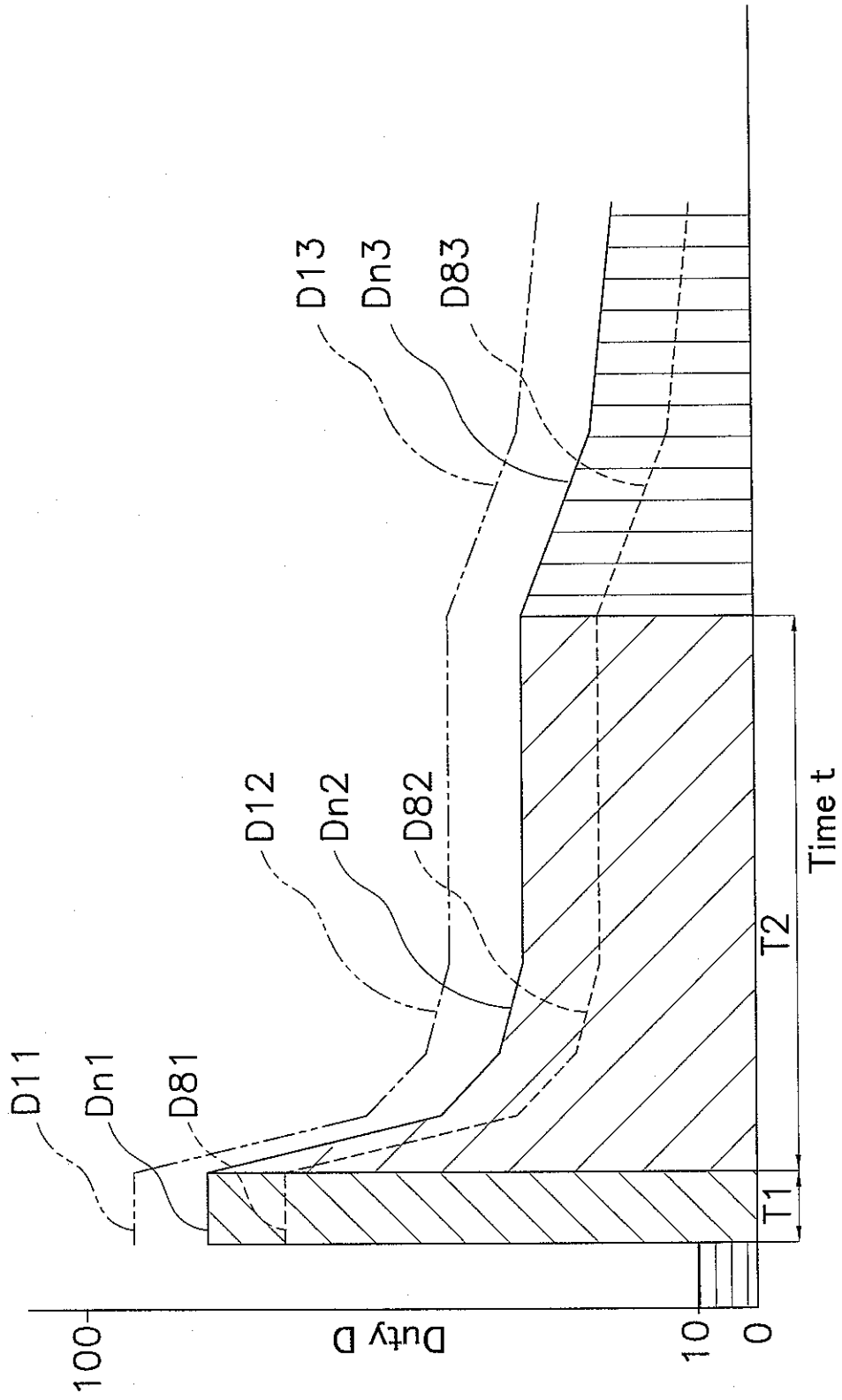


Figure 11B

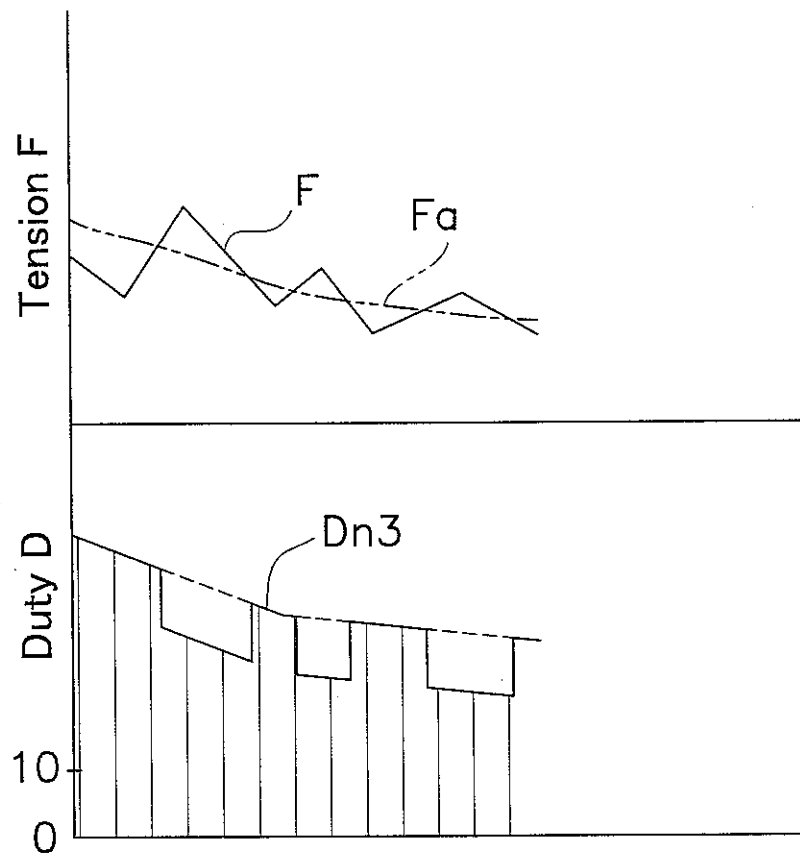


Figure 12

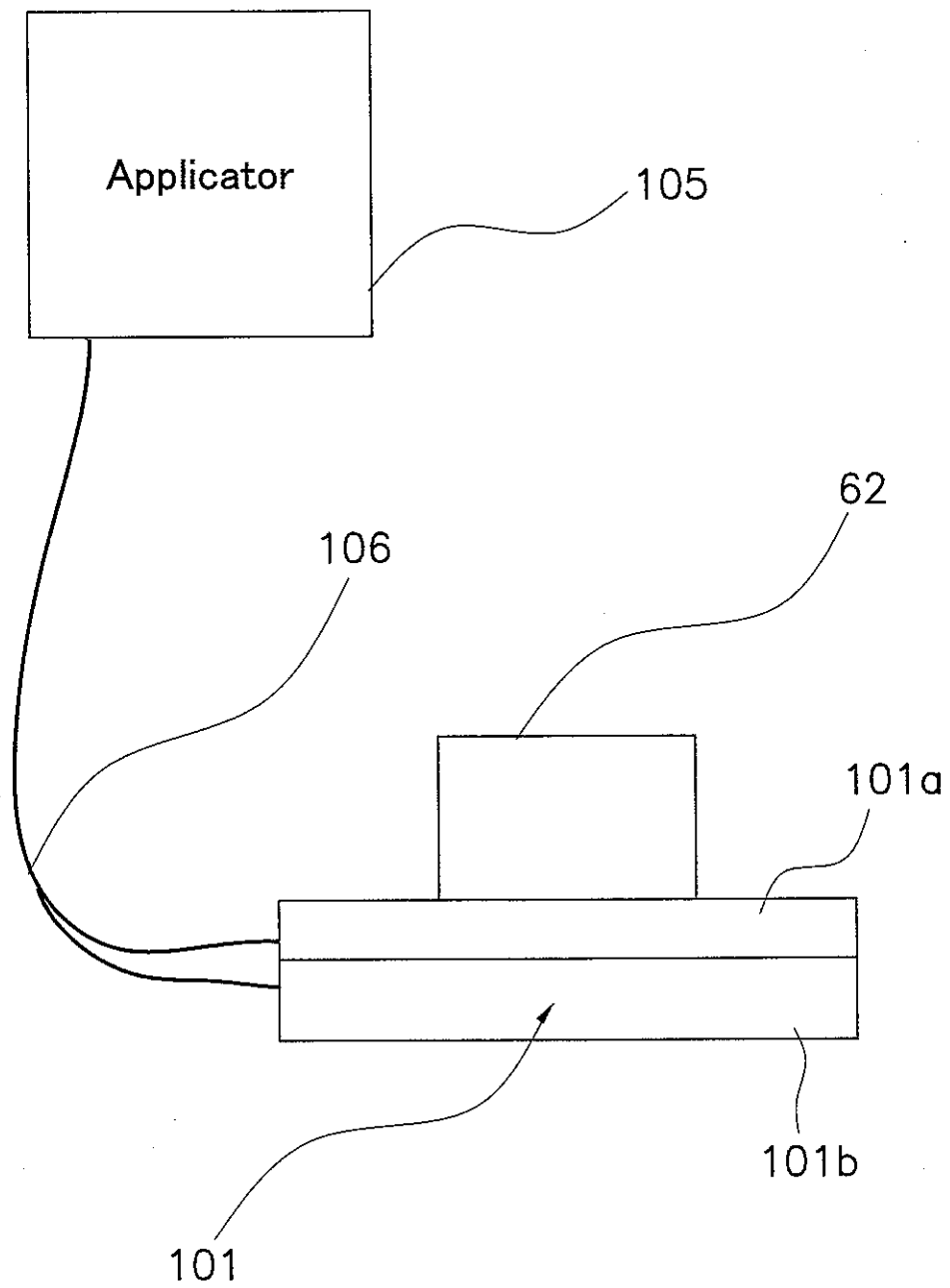


Figure 13

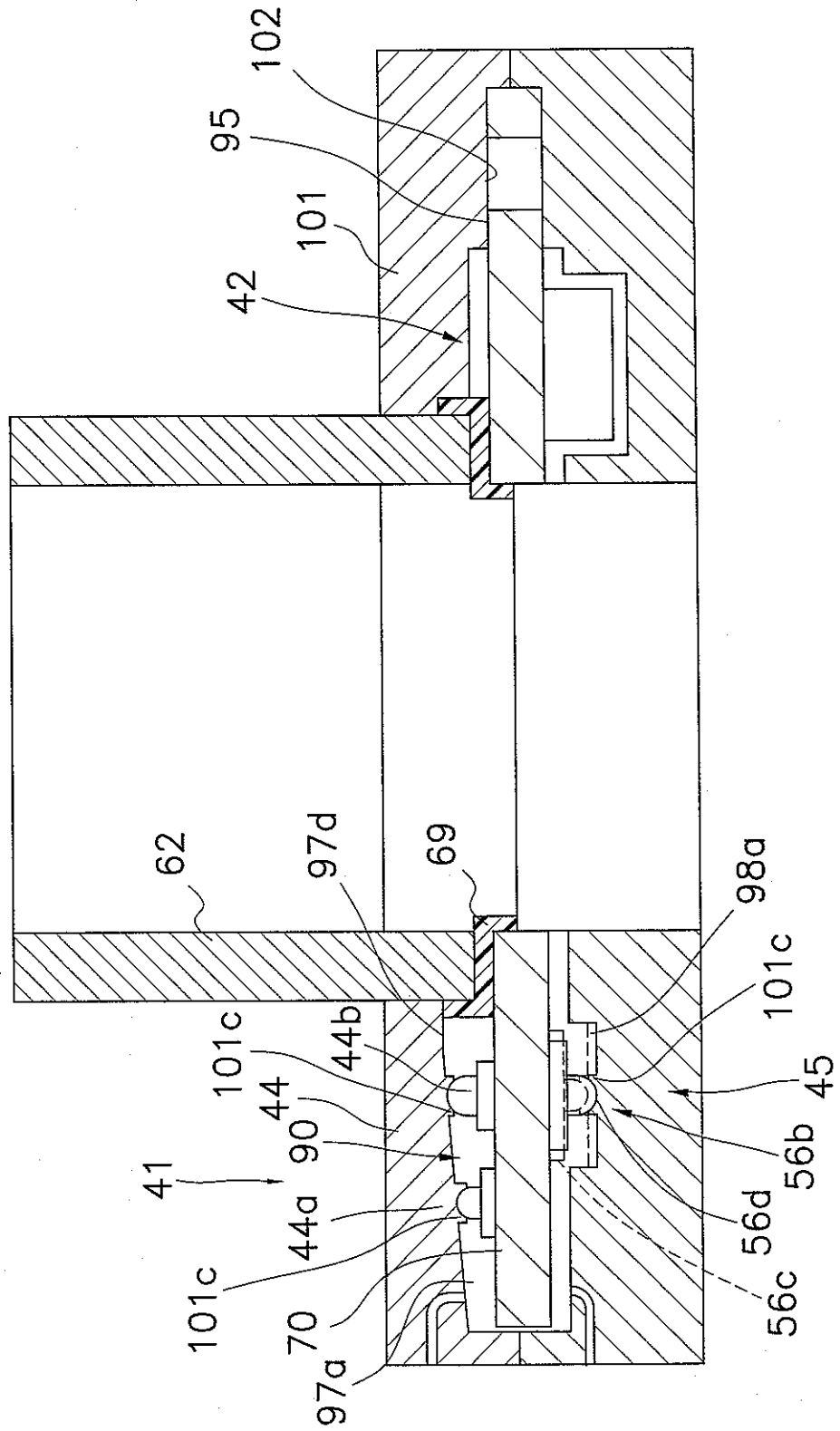


Figure 14

This diagram shows a cross-sectional view of a second embodiment of the semiconductor device. It features a central substrate with a central cavity. On the left side, there is a structure labeled 41, which includes a top layer with two circular features and a bottom layer with a central circular feature. A label 45 points to the bottom layer of this structure. On the right side, there is a structure labeled 62, which includes a top layer with a central rectangular feature and a bottom layer with a central rectangular feature. A label 70 points to the top layer of this structure. The entire device is mounted on a base labeled 101b. A downward arrow is shown at the bottom center of the diagram.

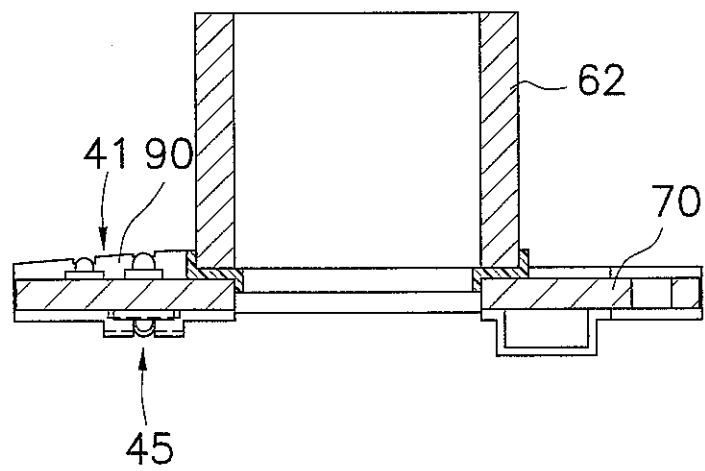
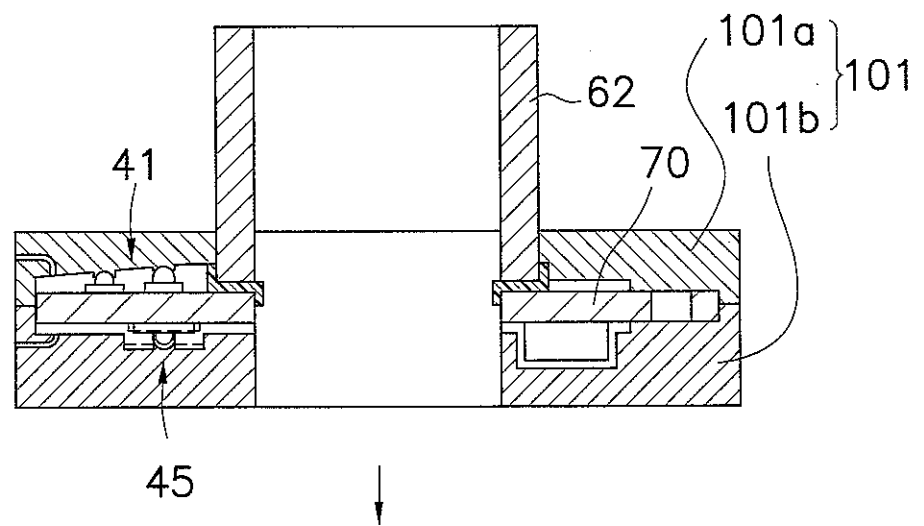


Figure 15

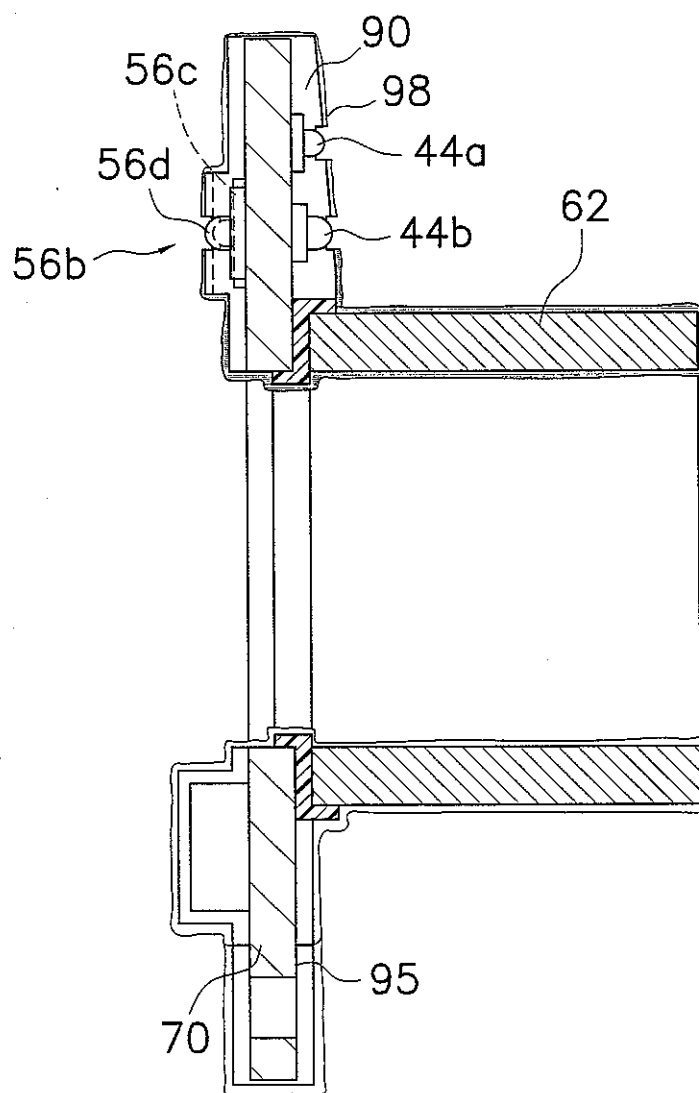


Figure 16